### PATENT ASSIGNMENT

## Electronic Version v1.1 Stylesheet Version v1.1

**SUBMISSION TYPE: NEW ASSIGNMENT** 

NATURE OF CONVEYANCE: **ASSIGNMENT** 

#### **CONVEYING PARTY DATA**

Name	Execution Date
DPAC Technologies Corp.	06/09/2004

#### RECEIVING PARTY DATA

Name:	Staktek Group L.P.
Street Address:	8900 SHOAL CREEK BLVD.
Internal Address:	SUITE 125
City:	Austin
State/Country:	TEXAS
Postal Code:	78701

#### PROPERTY NUMBERS Total: 8

Property Type	Number
Patent Number:	6222737
Patent Number:	6404043
Patent Number:	6426549
Patent Number:	6473308
Patent Number:	6544815
Patent Number:	6627984
Patent Number:	6660561
Patent Number:	RE39628

#### **CORRESPONDENCE DATA**

Fax Number: (512)906-2075

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

(512) 906-2201 Phone:

Email: lauff@civinsdenko.com

Correspondent Name: Steven Lauff

Address Line 1: 816 Congress Ave., Suite 1205

**REEL: 023870 FRAME: 0245** 

**PATENT** 

501080317

Address Line 2: Civins Denko C Address Line 4: Austin, TEXAS	Coburn & Lauff LLP 78701
ATTORNEY DOCKET NUMBER:	21260
NAME OF SUBMITTER:	Steven Lauff
Total Attachments: 10 source=46#page1.tif source=46#page2.tif source=46#page3.tif source=46#page4.tif source=46#page5.tif source=46#page6.tif source=46#page7.tif source=46#page8.tif source=46#page9.tif source=46#page9.tif source=46#page10.tif	

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06/08/04

# EXHIBIT A ASSIGNMENT OF DPAC ASSETS

WHEREAS, DPAC Technologies Corp. (formerly known as Dense-Pac Microsystems, Inc.) ("DPAC") owns certain intellectual properties consisting of inventions, patents, and patent applications (enumerated on attached and incorporated Exhibit 1) (the "DPAC Assets"):

WHEREAS, Staktek Group L.P., a Texas limited partnership, desires to acquire and DPAC desires to assign to Staktek Group L.P., all of DPAC's rights in the DPAC Assets;

NOW, THEREFORE, DPAC, for itself and its predecessors in interest for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, does hereby ASSIGN to Staktek Group L.P., all right, title and interest in the DPAC Assets, this assignment including, but not being limited to:

- 1. The ASSIGNED INVENTIONS enumerated on Exhibit 1 whether created by DPAC, its predecessors, its legal representatives or its assigns in the United States or any other country or place anywhere in the world;
  - 2. The ASSIGNED PATENTS enumerated on Exhibit 1;
  - The ASSIGNED PATENT APPLICATIONS enumerated on Exhibit 1;
- 4. All rights of action on account of past, present, and future unauthorized use or infringement of said DPAC Assets including, but not limited to all rights to damages so accrued;
- 5. The right, where allowed by law, to file in the name of Staktek Group L.P. applications for patent and like protection for any one or more of the DPAC Assets in any country or countries foreign to the United States;
- 6. All international and domestic rights or priorities associated with any one of the DPAC Assets; and

This Assignment shall be binding upon and shall mure to the benefit of the successors, assigns, and legal representatives of the parties.

DPAC STAKTEK

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EXECUTED on the EFFECTIVE DATE indicated below:

Assignor: DPAC TECHNOLOGIES CORP.

Date: JUNE 9, 2004

IDPAC TECHNOLOGIES CORP DENCERI

THE STATE OF CALIF

COUNTY OF [Oppnge]

This instrument was acknowledged by DPAC Officer on this the 9 day of

(Seal)

My commission expires:  $\frac{9/25/04}{}$ 

ROBERTA Y. HUFF Commission # 1278407 Natary Public - California **Orange County** My Comm. Explos Sep 25, 2004

Page 2 of 2 - Exhibit A

**DPAC** 

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Page 3 of 8 - Exhibit 1

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	6,472,735											-	6,544,815		Number	Trademark	7	)PAC
	3-D Nemory Stacking Using Anisotropic Epoxy Interconnects	Socketed Stacking	Internal Detectors for Capacitive Coupling Test	Heterogeneous Enhanced LP Stack	BGA Davice with Flax Flap	Stack	Spaces	FluxAladordill	Panel Stacking of BGA Devices to	Panel Stacking of BOA Devices to Form Three-Dimensional Modules	Form 3-D Modules	Punel Stacking of BGA Davisor in	Panel Stucking of BGA Devices to	ranci sucking of BUA Devices		Description		Assets
	layued. 3 1/2 year maintenance fees due 04/29/2006.	** Closed	Closed.	** Closed.	Closed.	Closed	Cloved.		** Closed.	Closed.	CIUSCO.	due 10/08/2006.	Issued. 3 1/2 year maintenance fees	** Closed.		Status		
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Page 5 of 8 - Exhibit 1

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AU8:357564.4	Packaged Integrated Circuit Chips	<u> </u>	3-D Stacking Thermal Ring Used in 1-D Stacking	Tost in a Ring Interconnect Used for 3-D Stacking	3-D Stacking	3-D Stacking	Reprinte Bins Interest		VO Interface Structure	Slice Interconnect Structure	Slice interconnect Structure	Interconnections Buried Device Stack	Using Anisotropic Enoxy		TitleMark - inventor	
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Page 6 of 8 – Exl	10/024,389	09/994,002	10/117,245	09/957,190	10/117,836	09/957,373	60/298,371	10/160,857	60/298,432	10/101/229	016.65		10/092,073	Serfol Number		EXHIBIT
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				6,573,460		6,573,461							Jack	Patent/ Trademark Registration		חפא ר
	Flex Tab Stacking	3-D Stacking Using Thermal Ring	Post in Ring Interconnect Using 3-D Stacking	Post in Ring Interconnect Using 3-D Stacking	Retaining Ring Interconnect Using 3-D ** Closed. Stacking	Remining Ring Interconcel Using 3-D Stacking	VO Interface Structure	VO interface Structure	Slice Interconnect Structure	Slice Interconnect Structure	Buried Device Stack	Anisotropic Epoxy Interconnects	3-D Memory Stacking Using	Description	AUDICES	Acopta
DPAC STAKTEK	** Closed.	** Closed.	** Clased.	lsaued. 3 1/2 year maintenance fees due 12/03/2006	** Closed.	Issued. 3 1/2 year maintenance fees due 12/03/2006	Utility Application Filed - See DENSE-045N	•• Closed.	Utility Application Filed - Sec DENSE-044N	Pending, Awaiting Receipt of Response to Restriction Requirement	** Clased.	Croscu.	Clark	Stanue		
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EXHIBIT I - DPAC ASSets   Description   Palest   Type   Trademick   Direct   Palest   Description   Palest   Des			DENSE-067S			1	PRNSE-066A	DENSE-065A	DENSE-062A		DENSH-061A	VO90 HEN 40	DENSE-059A		DENSE-055A	DENSE-053A	V2co-acuad	DENGE OCC	Care Care	Tr. Jan. J.		
Priest   Friest   F		ļ				<del>                                     </del>		T.S.O.P STACKING USING	Near Die Stack	000000	Processed Chip Scale Package	Integrated Z-Axis Interconnect on Door	Trench Transposer	CO TRUM	Innerconnect	Folded Flex Circuit with z-axis		,	Hary 28, 2004			
Pullog Serial Inva Date! Patenty Date Number Registration 121(4200) 100016,5399  Pullog Number Registration Require Registration Registrat			Patent		Patent		Patent	Patent	Paccut	Patent	Latedi		Patcnt	Patent	a icht	0	Patent	Item Type				
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I - DPAC ASSets	i			10/620,157	10/310,368	10/408,697						14,400,141	10/408 517			1		Serial Number		HIBIT		
ASSETS  Description  Description  C-S Slack with Double Sided Flox and Formed Lead  C-S Slack with Double Sided Flox and Formed Lead  C-S Slack with Double Sided Flox and Formed Lead  Formed Lead  C-S Slack with Double Sided Flox and Formed Lead  Fromed Lead  Closed.  Closed.  Closed.  Closed.  Closed.  Transparer  T	nbit 1																	Issue Date	,	-		
Description  Description  Description  Description  Description  Status  Require Recass Lead  Cos Stack with Double Sided Flex and Closed.  Cos Stack with Double Sided Flex and Closed.  Encronnect  Cos Stack with Double Sided Flex and Closed.  Corner A  Fridade Flix Circuit with r-axis  Closed.  Closed.  Closed.  Closed.  Closed.  Closed.  Pito  Pito Closed.  Closed.  Closed.  Closed.  Closed.  DPAC  Tight Stack Package  Closed.  Closed.  Closed.  Closed.  Closed.  DPAC  TASOP STACKING USING  OFFAC  TASOP STACKING USING  OFFAC  THIN SCALE OUTLINE PACKAGE  Response to OA due 6/24/04  PTO  THIN SCALE OUTLINE PACKAGE  Response to OA due 6/24/04  PTO  THIN SCALE OUTLINE PACKAGE  Response to OA due 6/24/04  PTO  THIN SCALE OUTLINE PACKAGE  Response to OA due 6/24/04  PTO  TASOP STACK PATENT SEARCH  Patent Sauch Opinion Letter to client  N/A  DPAC  DPAC  TASOP STACK PATENT SEARCH  PTO  DPAC  TASOP STACK PATENT SEARCH  PTO  DPAC  DPA												<del>/**** '</del>					Number					
Accion Require Require PTO DPAC DPAC DPAC DPAC DPAC DPAC DPAC DPAC		1.S.O.P STACK PATENT SEARCH	STACK	THIN SCALB OUTLINE PACKAGE	THIN SCALB OUTLING PACKAGE STACK	UNDERLEAD INTERPOSER	LASENSPOT WELDING INTERCONNECT		Near Die Sinck	Direct Die Scale	Processed Chip Scale Package	French Fransposor		CS-STACK	Folded Flox Circuit with z-axis Innerconnect	C-S Stack with Double Sided Flex and Formed Lead			CXDOCCD	Accete		
	DPAC	Patent Search Opinion Letter to client 12/31/2002.	Restriction Requirement	Awaiting Receipt of Response to	Response to OA due 6/24/04	** Closed.	Closed (Combined with DENSE- 067A)	Civacu		Closed.	Closed	•• Closed.		Closed.	Closed.	1 ** Clased.		Status		And the second s		
\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\		X X	2	DPAC	OIA	OLd	N/A	DPAC		DPAC	DPAC	PTO		N/A	DPAC	PTO	Owner	Require				
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	DENSE-072A	DENSE-071N	DENSE 070A	DENSB-069A	DENSE-068A		Case	Updated: January 28, 2004		
STOCK PINEWINGENENIN	DENSE-072A TSOP STACE BY A STACE	DENNE-071N METUOD TO ACCREG TO A ROOTING	MONOLITHIC TO STACKABLE	DENSE-069A TRANSPOSER CONTRACTOR FOR	DENSE-068A T.S.O.P. POLYIMIDE FILM STRIP		Tille/Mark - Invention	uary 28, 2004		
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					Januari	Trademark Registration	Patent/		EXHIBIT 1 - DPAC Assets	
ISOP STACK ENHANCEMENTS	METHOD TO ACCESS SCALABLE Closed AKRAYS OF MEMORY VIA HYPER TRANSPORT BUSES	STAIR-STEP SIGNAL ROUTING	TRANSPOSER CONVERTER FOR MONOLITHIC TO STACKABLE	STACK	T.S.O.P. POLYNMER FILM STRIP		Description		ssets	
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